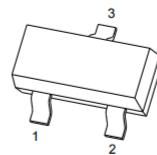


| $V_{(BR)DSS}$ | $R_{DS(on)}\text{MAX}$ | I_D |
|---------------|------------------------|-------|
| 30V | 0.057Ω@ 10V | 3.6 A |
| | 0.094Ω@ 4.5V | |

SOT-23


 1.GATE
 2.SOURCE
 3.DRAIN

General FEATURE

- TrenchFET Power MOSFET
- Lead free product is acquired
- Surface mount package

Equivalent Circuit

APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Maximum | | Units |
|--|----------------|------------|----|-------|
| Drain-Source Voltage | V_{DS} | 30 | | V |
| Gate-Source Voltage | V_{GS} | ± 20 | | V |
| Continuous Drain Current ^A | I_D | 3.6 | | A |
| Pulsed Drain Current ^B | | | 15 | |
| Power Dissipation ^A | P_D | 1.4 | | W |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|--|-----------------|-----|-----|-------|
| Maximum Junction-to-Ambient ^A | $R_{\theta JA}$ | 70 | 90 | °C/W |
| Maximum Junction-to-Ambient ^A | | 100 | 125 | °C/W |
| Maximum Junction-to-Lead ^C | $R_{\theta JL}$ | 63 | 80 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------------------------|---------------------------------------|--|-----|------|-----|------------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$ | 30 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$ | | | 1 | μA |
| I_{GSS} | Gate-Body leakage current | $V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$ | | | 100 | nA |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}$ $I_D=250\mu\text{A}$ | 1 | 1.5 | 2 | V |
| $I_{D(\text{ON})}$ | On state drain current | $V_{GS}=10\text{V}$, $V_{DS}=5\text{V}$ | 15 | | | A |
| $R_{DS(\text{ON})}$ | Static Drain-Source On-Resistance | $V_{GS}=10\text{V}$, $I_D=3.6\text{A}$ | | 50 | 57 | $\text{m}\Omega$ |
| | | $V_{GS}=4.5\text{V}$, $I_D=2.8\text{A}$ | | 88 | 94 | $\text{m}\Omega$ |
| g_{FS} | Forward Transconductance | $V_{DS}=5\text{V}$, $I_D=3.6\text{A}$ | | 11 | | S |
| V_{SD} | Diode Forward Voltage | $I_S=1\text{A}$ | | 0.79 | 1 | V |
| I_S | Maximum Body-Diode Continuous Current | | | | 2.5 | A |
| DYNAMIC PARAMETERS | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V}$, $V_{DS}=15\text{V}$, $f=1\text{MHz}$ | | 230 | | pF |
| C_{oss} | Output Capacitance | | | 40 | | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 17 | | pF |
| R_g | Gate resistance | $V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$ | | 3 | 6 | Ω |
| SWITCHING PARAMETERS | | | | | | |
| Q_g | Total Gate Charge | $V_{GS}=10\text{V}$, $V_{DS}=15\text{V}$, $I_D=3.6\text{A}$ | | 4.0 | | nC |
| Q_{gs} | Gate Source Charge | | | 0.75 | | nC |
| Q_{gd} | Gate Drain Charge | | | 0.65 | | nC |
| $t_{D(\text{on})}$ | Turn-On Delay Time | $V_{GS}=4.5\text{V}$, $V_{DS}=10\text{V}$, $I_D=3.6\text{A}$, $R_{\text{GEN}}=3\Omega$ | | 10 | | nS |
| t_r | Turn-On Rise Time | | | 50 | | nS |
| $t_{D(\text{off})}$ | Turn-Off Delay Time | | | 10 | | nS |
| t_f | Turn-Off Fall Time | | | 20 | | nS |

A: The value of R_{JLA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R_{JLA} is the sum of the thermal impedance from junction to lead R_{JL} and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

Rev 5 : July 2005

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

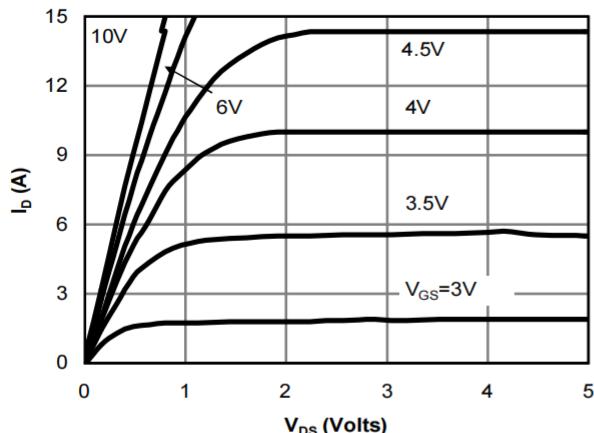


Fig 1: On-Region Characteristics

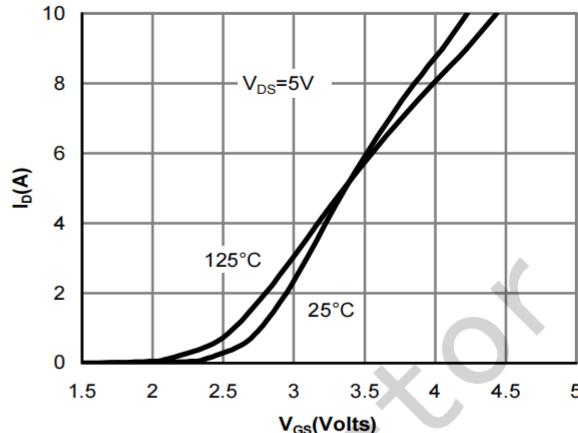


Figure 2: Transfer Characteristics

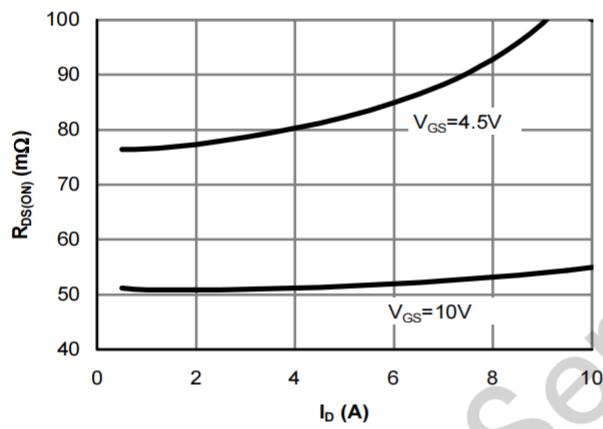


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

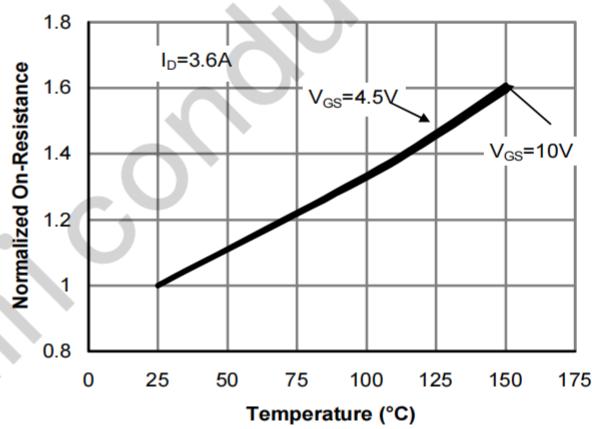


Figure 4: On-Resistance vs. Junction Temperature

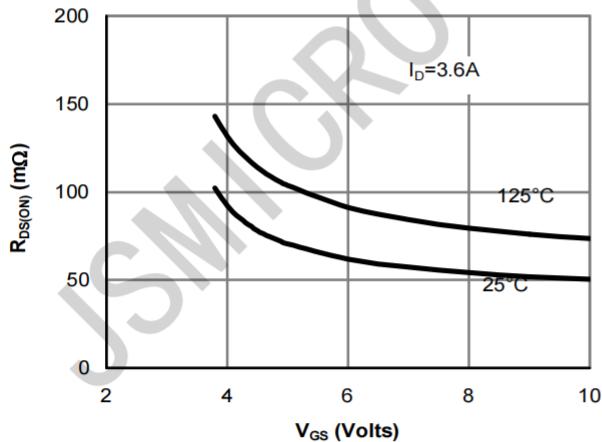


Figure 5: On-Resistance vs. Gate-Source Voltage

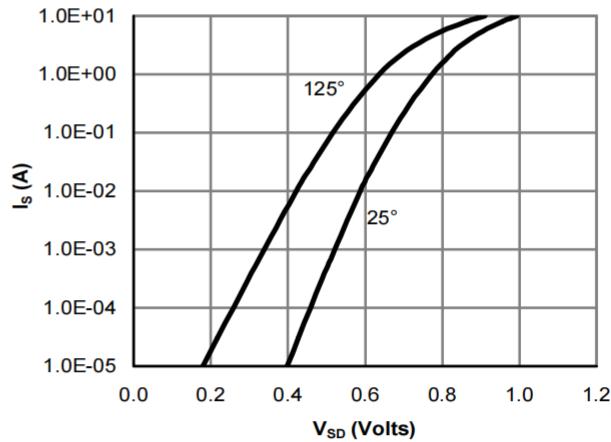


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

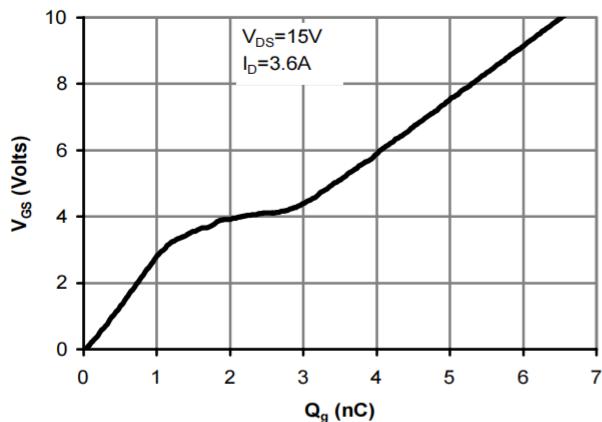


Figure 7: Gate-Charge Characteristics

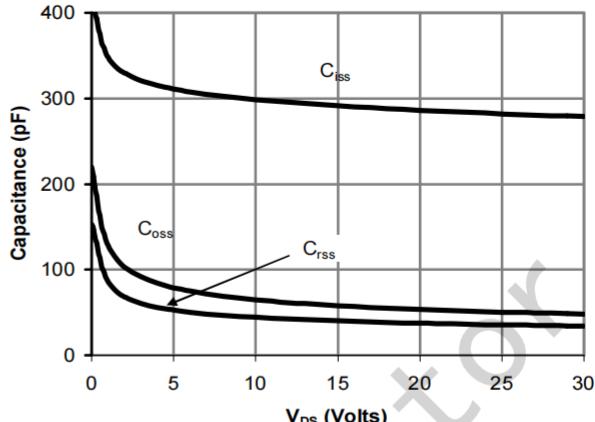


Figure 8: Capacitance Characteristics

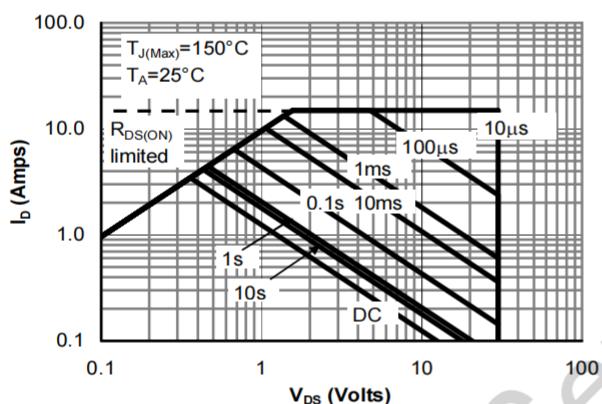


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

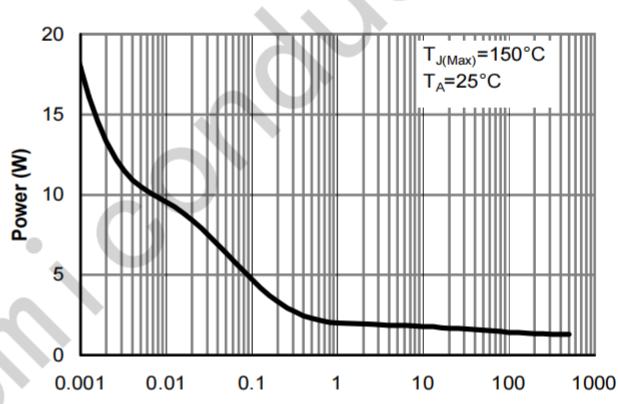


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

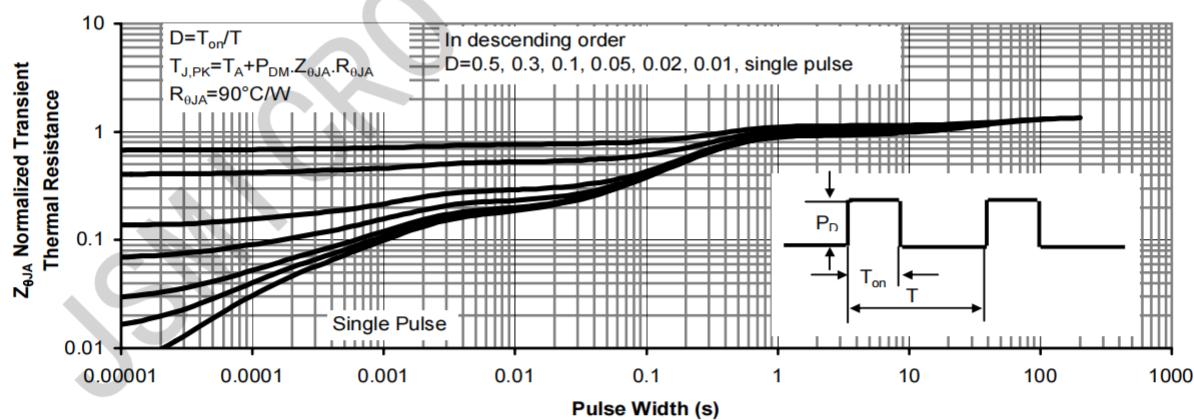
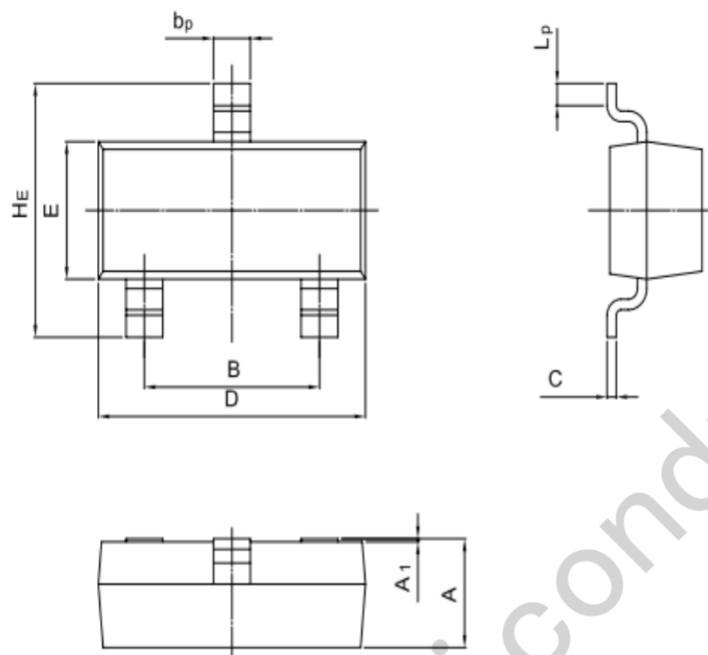


Figure 11: Normalized Maximum Transient Thermal Impedance

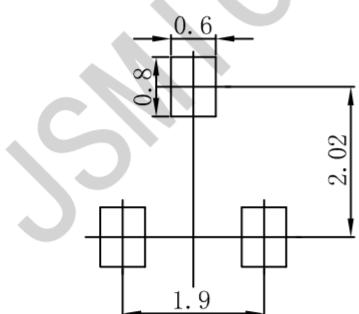
Package Information

SOT-23



| UNIT | A | B | b _p | C | D | H _E | A ₁ | L _p |
|------|--------------|--------------|----------------|--------------|--------------|----------------|----------------|----------------|
| mm | 1.40 0.95 | 2.04 1.78 | 0.50 0.35 | 0.19 0.08 | 3.10 2.70 | 1.65 1.20 | 3.00 2.20 | 0.100 0.013 |
| | | | | | | | | 0.50 0.20 |

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.